

Dymax 9001v3.1 Resilient, Low Modulus Clear Microencapsulant

Category : Polymer , Adhesive , Thermoset

Material Notes:

High Performance Light-Curing Adhesives and Coatings for Electronic Assembly Dymax 9001v3.1 Resilient, Low Modulus Clear

Microencapsulant Lowest stress potting and encapsulation on ceramic, FR-4 or flexible PCBs Cure Type: UV/Visible Typical Use: Glob top, chip on board, "smart cards"

Order this product through the following link:

http://www.lookpolymers.com/polymer_Dymax-9001v31-Resilient-Low-Modulus-Clear-Microencapsulant.php

Physical Properties	Metric	English	Comments
Viscosity	4500 cP	4500 cP	

Optical Properties	Metric	English	Comments
Transmission, Visible	90 %	90 %	clear; thickness not quantified

Processing Properties	Metric	English	Comments
Cure Time	0.0333 - 0.250 min	0.000556 - 0.00417 hour	10-20 mil thick layers cured with Dymax 5000-EC at 2 inches. Thicker layers may require more cure time.

Descriptive Properties	Value	Comments
Color	Clear	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China